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# MOSFET – Power, Single N-Channel 60 V, 26.5 m $\Omega$ , 20 A

#### **Features**

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVTFS5C680NLWF Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parar	Symbol	Value	Unit		
Drain-to-Source Voltag	$V_{DSS}$	60	V		
Gate-to-Source Voltage	Э		V <sub>GS</sub>	±20	V
Continuous Drain		T <sub>C</sub> = 25°C	I <sub>D</sub>	20	Α
Current R <sub>θJC</sub> (Notes 1, 2, 3, 4)	Steady	T <sub>C</sub> = 100°C		14	
Power Dissipation	State	T <sub>C</sub> = 25°C	$P_{D}$	20	W
R <sub>θJC</sub> (Notes 1, 2, 3)		T <sub>C</sub> = 100°C		10	
Continuous Drain		T <sub>A</sub> = 25°C	I <sub>D</sub>	7.82	Α
Current R <sub>θJA</sub> (Notes 1 & 3, 4)	Steady State	T <sub>A</sub> = 100°C		6.54	
Power Dissipation		T <sub>A</sub> = 25°C	$P_{D}$	3.0	W
R <sub>θJA</sub> (Notes 1, 3)		T <sub>A</sub> = 100°C		2.1	
Pulsed Drain Current	$T_A = 25$	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	80	Α
Operating Junction and	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C		
Source Current (Body D	I <sub>S</sub>	17	Α		
Single Pulse Drain-to-S Energy (I <sub>L(pk)</sub> = 1 A)	E <sub>AS</sub>	51	mJ		
Lead Temperature for S (1/8" from case for 10 s)	TL	260	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL RESISTANCE MAXIMUM RATINGS (Note 1)

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State (Note 3)	$R_{\theta JC}$	7.32	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	49	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi  $(\Psi)$  is used as required per JESD51–12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- Continuous DC current rating. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

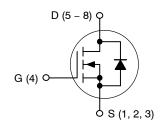


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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX	
60 V	26.5 mΩ @ 10 V	20 A	
	42.5 mΩ @ 4.5 V	20 A	

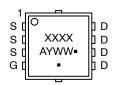
#### N-Channel





#### WDFN8 (μ8FL) CASE 511AB

#### **MARKING DIAGRAM**



XXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•					•	•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C			10	μΑ
		V <sub>DS</sub> = 60 V	T <sub>J</sub> = 125°C			100	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{G}$	<sub>S</sub> = +20 V			100	nA
ON CHARACTERISTICS (Note 5)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{E}$	ο = 13 μΑ	1.2		2.2	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I	<sub>D</sub> = 10 A		22	26.5	mΩ
		V <sub>GS</sub> = 4.5 V,	I <sub>D</sub> = 10 A		34	42.5	1
Forward Transconductance	9 <sub>FS</sub>	V <sub>DS</sub> = 15 V, I	<sub>D</sub> = 10 A		20		S
CHARGES AND CAPACITANCES							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V, f} = 1.0 \text{ MHz,}$ $V_{DS} = 25 \text{ V}$			327		pF
Output Capacitance	C <sub>oss</sub>				161		
Reverse Transfer Capacitance	C <sub>rss</sub>				6.0		
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS} = 48 \text{ V}, I_D = 10 \text{ A}$			2.9		nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				0.8		nC
Gate-to-Source Charge	$Q_{GS}$				1.2		1
Gate-to-Drain Charge	$Q_{GD}$				8.0		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> =	48 V, I <sub>D</sub> = 10 A		6.0		nC
SWITCHING CHARACTERISTICS (No	ote 6)						
Turn-On Delay Time	t <sub>d(on)</sub>				6.5		ns
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V	<sub>DS</sub> = 48 V,		25		
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS} = 4.5 \text{ V, V}_{D}$	$\frac{1}{3} = 1.0 \Omega$		13		1
Fall Time	t <sub>f</sub>	1			23		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	$V_{SD}$	$V_{GS} = 0 V$	T <sub>J</sub> = 25°C		0.9	1.2	V
		I <sub>S</sub> = 10 A	T <sub>J</sub> = 125°C		0.8		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS}$ = 0 V, $dI_S/dt$ = 100 A/ $\mu$ s, $I_S$ = 10 A			17		ns
Charge Time	t <sub>a</sub>				8.0		1
Discharge Time	t <sub>b</sub>				9.0		1
Reverse Recovery Charge	$Q_{RR}$				7.0		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

6. Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**

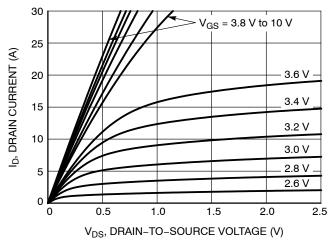


Figure 1. On-Region Characteristics

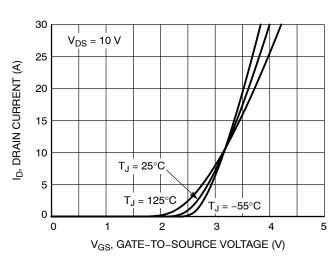


Figure 2. Transfer Characteristics

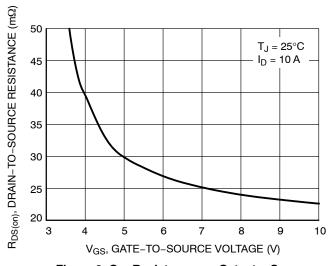


Figure 3. On-Resistance vs. Gate-to-Source Voltage

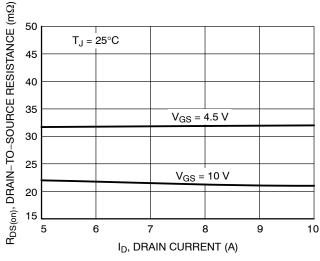


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

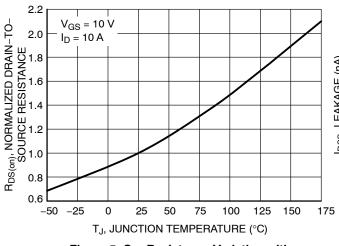


Figure 5. On–Resistance Variation with Temperature

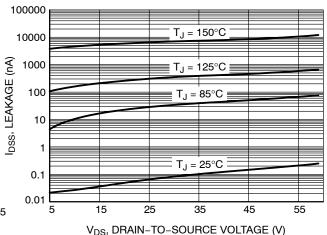


Figure 6. Drain-to-Source Leakage Current vs. Voltage

#### **TYPICAL CHARACTERISTICS**

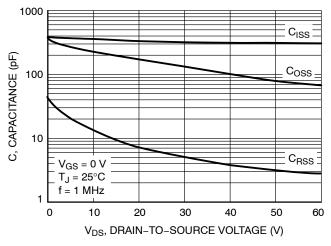


Figure 7. Capacitance Variation

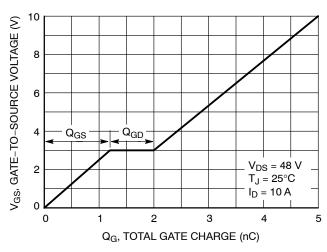


Figure 8. Gate-to-Source vs. Total Charge

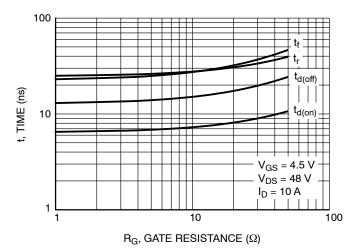


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

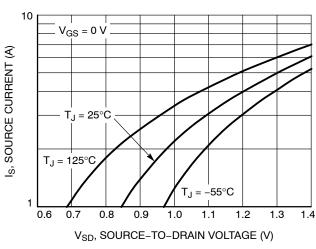


Figure 10. Diode Forward Voltage vs. Current

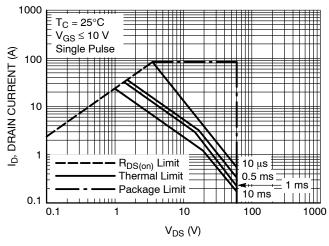


Figure 11. Maximum Rated Forward Biased Safe Operating Area

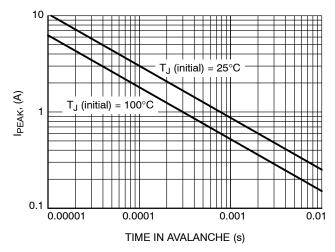


Figure 12. I<sub>PEAK</sub> vs. Time in Avalanche

#### **TYPICAL CHARACTERISTICS**

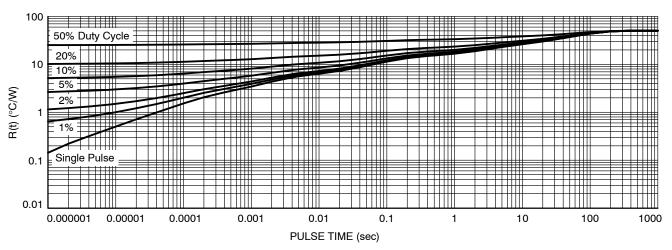


Figure 13. Thermal Characteristics

#### **DEVICE ORDERING INFORMATION**

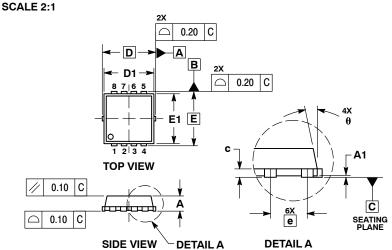
Device	Marking	Package	Shipping <sup>†</sup>
NVTFS5C680NLTAG	680L	WDFN8 (Pb-Free)	1500 / Tape & Reel
NVTFS5C680NLWFTAG	80LW	WDFN8 (Pb-Free)	1500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



#### WDFN8 3.3x3.3, 0.65P CASE 511AB ISSUE D

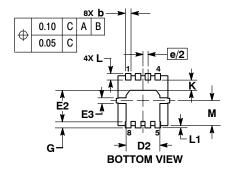
**DATE 23 APR 2012** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH
  PROTRUSIONS OR GATE BURRS.

	MILLIMETERS				<b>INCHES</b>		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D		3.30 BSC		0.130 BSC			
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E	3.30 BSC			0.130 BSC			
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е		0.65 BSC	;	0.026 BSC			
G	0.30	0.41	0.51	0.012	0.016	0.020	
K	0.65	0.80	0.95	0.026	0.032	0.037	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
М	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	



#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

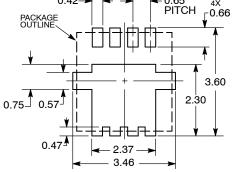
= Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

# PACKAGE OUTLINE

**SOLDERING FOOTPRINT\*** 



DIMENSION: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WDFN8 3.3X3.3. 0.65P	•	PAGE 1 OF 1	

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